

系所組別：電機工程學系甲組

考試科目：電子材料概論

考試日期：0307，節次：2

※ 考生請注意：本試題 可 不可 使用計算機

1. Explain the following noun. (20%)

- a). Ionic Polarization
- b). Interfacial Polarization
- c). Orientation Polarization
- d). Electrical Polarization
- e). Paramagnetism
- f). Ferromagnetism
- g). Frenkel defect
- h). Schottky defect
- i). Gibbs phase rule
- j). The level rule

2. Calculate the drift mobility and mean scattering time of conduction electrons in copper at room temperature , given that the conductivity of copper is $5.9 \times 10^5 \Omega^{-1} \cdot \text{cm}$. The density of copper is 8.96 g/cm^3 and its atomic mass is 63.5 g/mol .(20%)
3. Calculate the atomic packing factor (APF) for BCC unit cell, assuming the atoms to be hard spheres.(10%)
4. The diffusivity of silver atoms in solid silver metal is $1 \times 10^{-17} \text{ m}^2/\text{s}$ at 500°C and $1 \times 10^{-13} \text{ m}^2/\text{s}$ at 1000°C . Calculate the activation energy (joules/mole) for the diffusion of Ag in Ag at the temperature range from 500°C to 1000°C (20%)
5. Draw the following direction vectors in cubic unit cells(10%)
- (a). [100] and [110]
 - (b) [112]
 - (c) [-110]
 - (d) [-321]
6. A copper-nickel alloy contains 47 wt% Cu and 53 wt% Ni at 1300°C , Using Fig.1 and answer the following: (20%)
- (a). What is the weight percent of copper in the liquid and solid phases at this temperature?
 - (b) What weight percent of this alloy is liquid and what weight percent is solid?

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Fig.(1)

